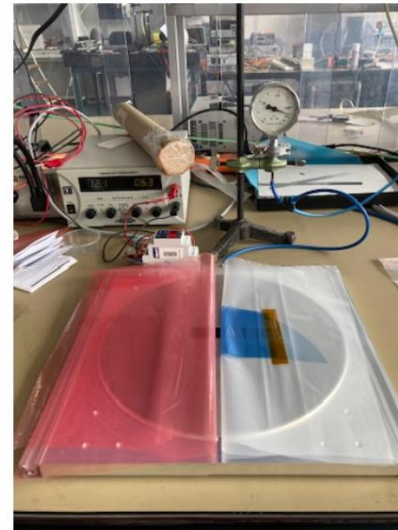
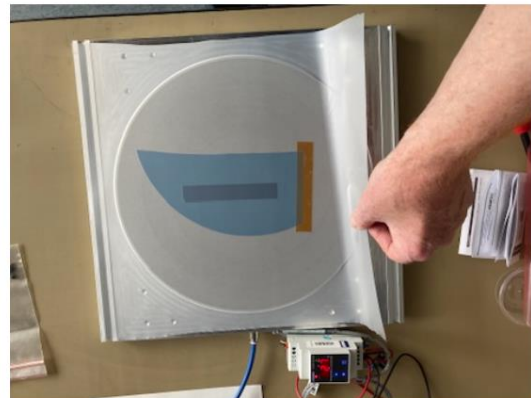
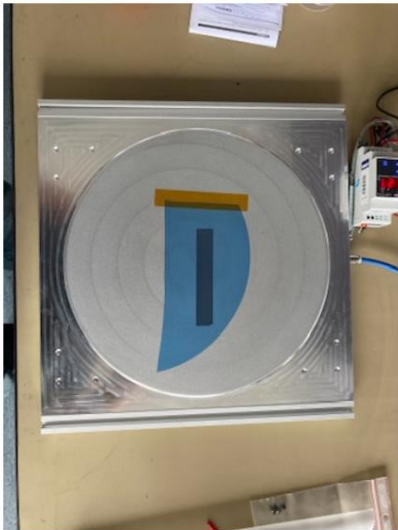
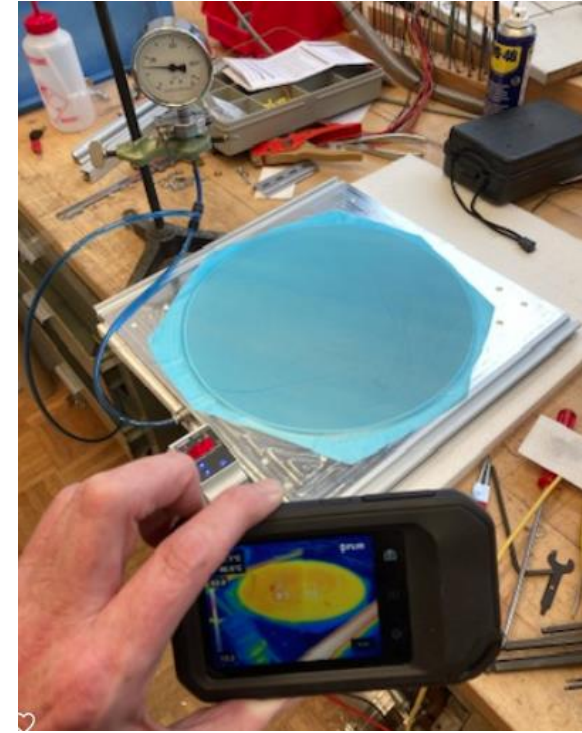


## Metapor table test

A couple sheets of silicon are send to Utrecht (thanks elisa/massimo)  
After peeling full waver try here table will be send to CERN



## Thermal expansion test silicon/carbon



Glued 0.1x2mm carbon to 0.05x3mm silicon cured on 80C



@20C radius is about 700mm silicon is on inner radius  
Difference in thermal expansions approx  $1.3e-6$  based on thickness/radius  
Carbon from toryca is  $-0.4$  to  $-1 e-6$  silicon  $2.6 e6$  so does not really match  
(take e-modulus in account ?)



Its straight at around 100C

Could use temperature while curing to advantage to keep silicon under compression !

## Question

What is the plan to test thermal stability of “mainline” design ?

Would it be useful to build a “utrecht design with mechanical decoupling to CIF” in silicon and test Thermal cycling ?

